HT10000-R High Thermal Conductive Gel

BENEFITS AND FEATURES

- 10 W/m.K thermal conductivity
- 1 part mateial, no curing process, friendly to automation
- Good wettability to interfaces
- Low assembly stress
- High thixotropy, low risk of slumping

TYPICAL APPLICATIONS

- Data center
- Optical modules
- Electronics for telecom
- Memories & consumer electronics
- Smart phone, PC

OVERVIEW

Honeywell 1 part thermal gel HT10000-R provides 10W/m.K thermal conductivity for those applications in high heat density. It is for those applications with big gap and it obsorbs various tolerances in module level. Different from traditional thermal gap pads, assembly force of HT10000-R is even lower and this benefits the electronics that is sensitive to pressure.

STORAGE & USE

Shelf Life: 12 months at 0-35°C, <65%RH

Property	HT10000-R	Test Method
Color	Light- grey	By visual
Thermal Conductivity (W/m· K)	10.0	ASTM D5470
Specific gravity	3.2	ASTM D792
Flow rate (g/min)	22	30cc EFD tube in 2.5mm diameter, 90 psi
Minimum BLT (μm)	200	NA
Dielectric strength (KV/mm)	>5	ASTM D149
Volume resistivity (Ohm.cm)	$1.0x10^{13}$	ASTM D257
Flame retardancy	V-0	UL 94 equivalent
Siloxane content (D3-D10) (ppm)	<100	GCMS
Working temperature	-50-150°C	HON internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102

Mainland China: 400-842-8487

Germany: 49-5137-999-9199

Japan: 81-3-6730-7092

Korea: 82-2-3483-5076

Singapore: 65-6580-3593

Taiwan: 886-3-6580300 ext.312

www.electronicmaterials.com